



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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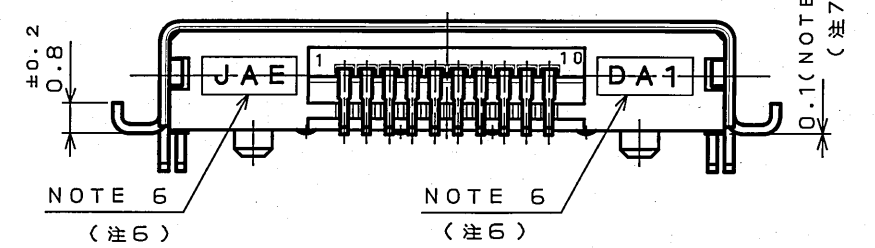
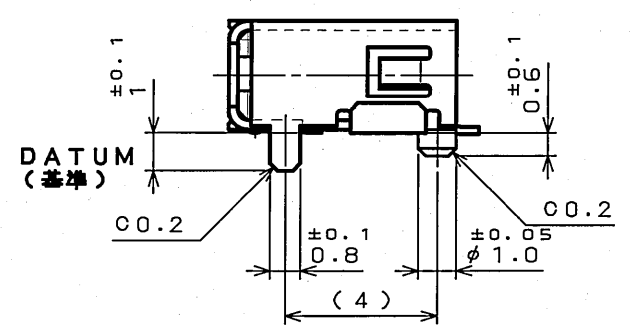
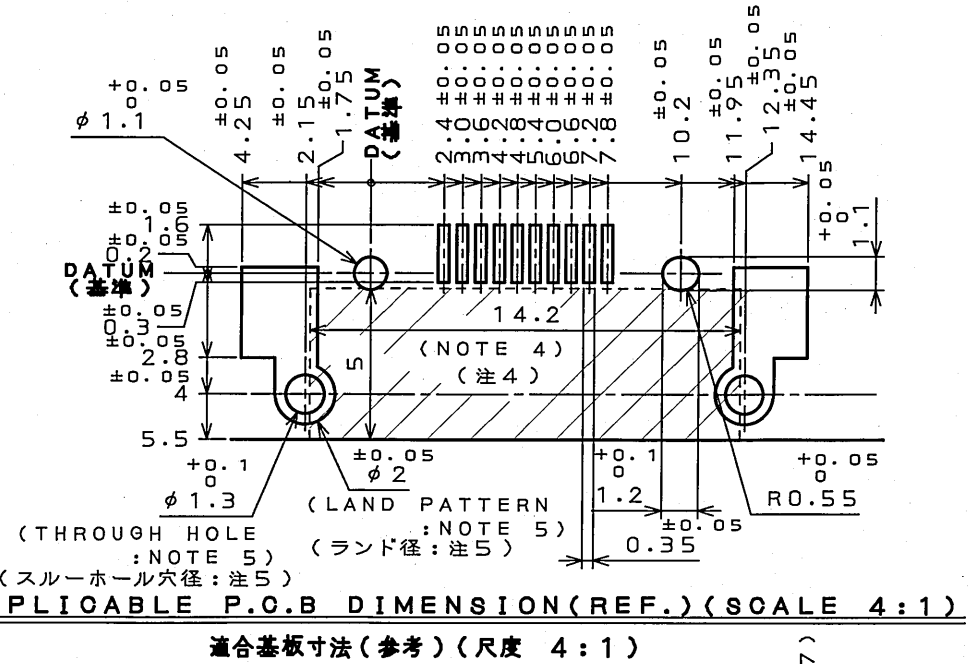
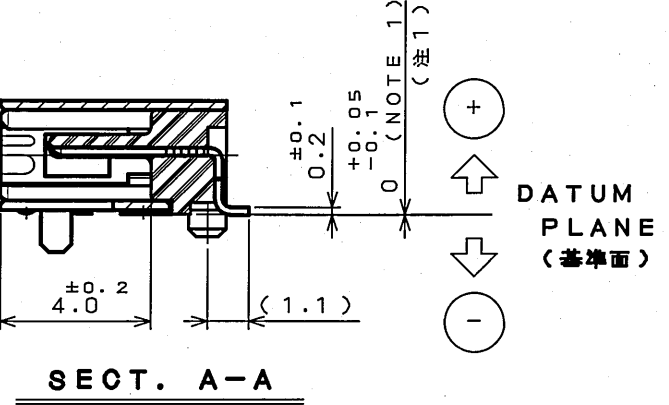
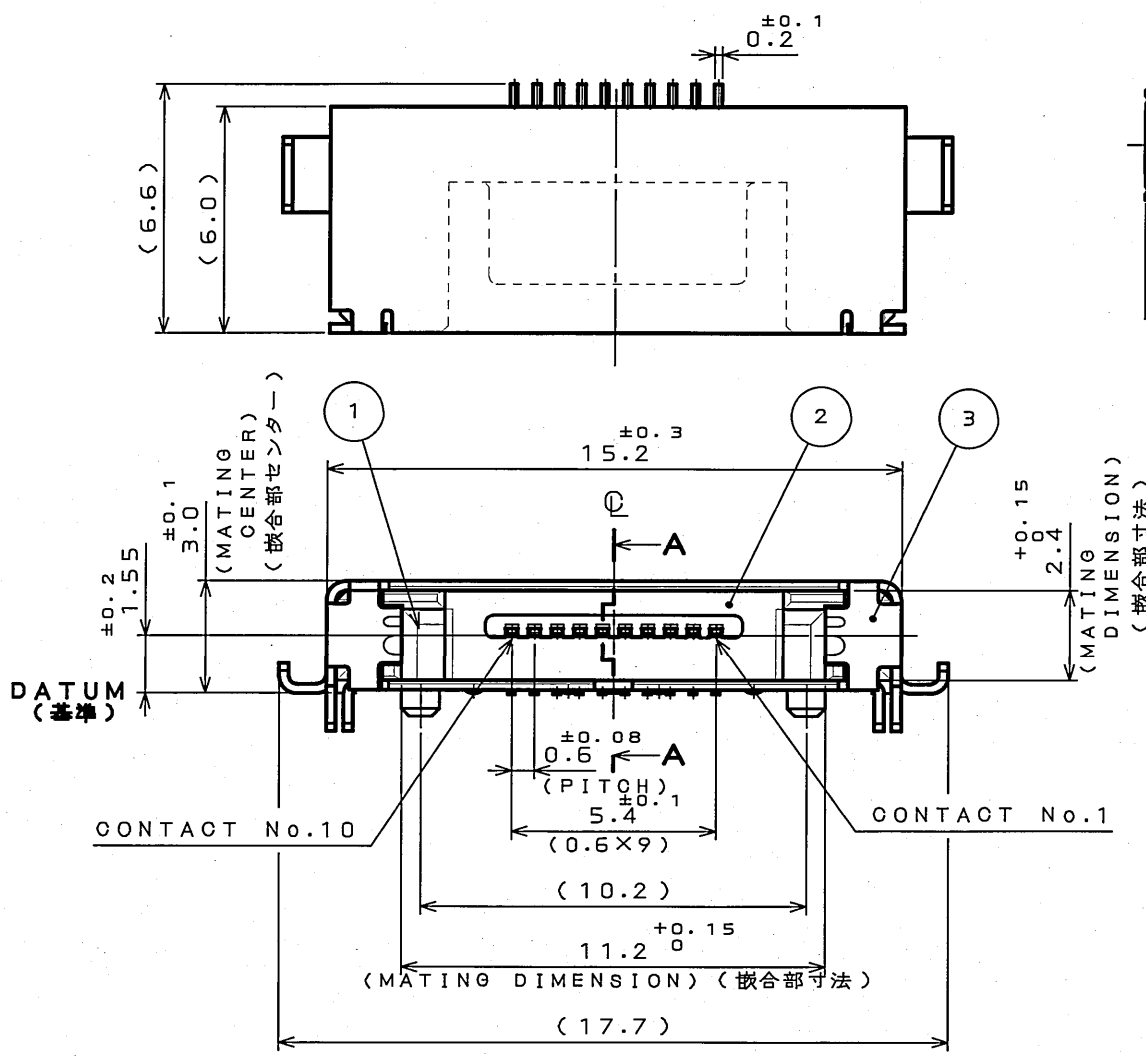
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



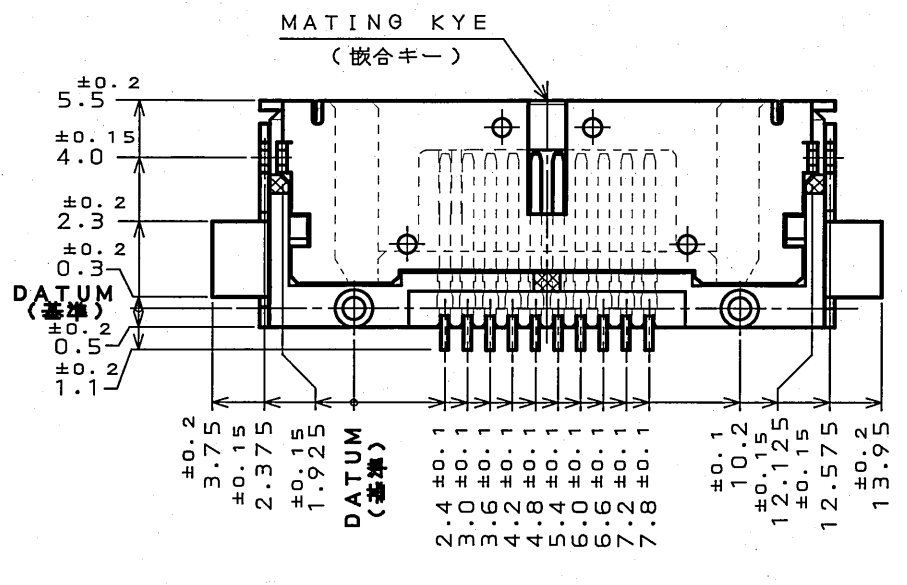
SJ038450
(DRAWING NO.)

- 注1. SMT公差部のプラス、マイナスの方向を示す。端子寸法は $0^{+0.05}_{-0.1}$ であり公差内におけるバラツキ(1コネクタ内のMAX値とMIN値の差)は、0.1以下とする。
- △2. 接触部は、ニッケル(1.5μm以上)上パラジウムニッケル(0.4μm以上)上金フラッシュメッキ(0.03μm以上)結線部は、ニッケル(1.5μm以上)上金フラッシュメッキ(0.03μm以上)である。
3. 本コネクタシェル半田付部破断面には、メッキは施されません。
4. 本斜線部内にはパターンを配線しないよう願います。
5. ランドは基板の両面に設けること。又、φ1.3の穴はスルーホールメッキであること。
6. 図示の位置に社標 "JAE" 及び品名 "DA1" を表示する。
7. 基板にのせた状態でホールドダウン部の浮きは0.1以下のこと。

版数 REV.	年月日 DATE	DCN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	16.06.2004	056414	FINISH CHANGE、OTHERS		Y.TAKAGI		<i>J. Kubota</i>



- NOTE 1. ⊕ AND ⊖ DENOTE ARE DIRECTION OF SMT TOLERANCE. TERMINAL DIMENSION IS $0^{+0.05}_{-0.1}$, AND DEVIATION (DIMENSION BETWEEN MINUS VALUE & PLUS VALUE) SHALL BE 0.1 MAX.
- △ 2. THE CONNECTING AREA IS PLATED WITH GOLD FLASH (0.03μm/in) OVER Pd-Ni (0.4μm/in) OVER NICKEL (1.5μm/in). THE TERMINAL AREA IS PLATED WITH GOLD FLASH (0.03μm/in) OVER NICKEL (1.5μm/in).
3. THE SHEARED EDGES OF CONNECTOR SHELL AT THE SOLDER AREA ARE NOT PLATING.
4. PLEASE NO PATTERNING IN SLANT AREA.
5. LAND MARK BOTH SIDES OF P.C.B. HOLE OF φ1.3 IS THROUGH HOLE PLATED.
6. COMPANY LOGO "JAE" AND PART NUMBER "DA1" ARE MARKED AS INDICATED.
7. THE FLOATAGE OF THE HOLD DOWN AREA IN 0.1mm MAX WHILE PUT ON THE P.C.B.



符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
3	SHELL	1	STAINLESS STEEL	(LEAD FREE) TIN/TIN ALLOY	
2	INSULATOR	1	PPS		UL94V-0
1	CONTACT	10	COPPER ALLOY	NOTE 2	
仕様書 (SPECIFICATION) JACS-3192		第1版 (ORIGINAL DATE) 3.Mar.2003		尺度 (SCALE) 5:1	シリーズ (SERIES) DA1
製図 DR. H.SAKURADA		担当 CHK. Y.TAKAGI		名称 (TITLE) DA1R010H91E	
査閲 APPD.		承認 APPD. Y.KUBOTA		質量 (MASS)	
図面番号 (DRAWING NO.) SJ038450		版数 (REV.) 2		日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.	

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